

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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12 281 FR4 35 L20.70 P10_06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

12_281_FR4_35_L20.70_p10_06

Layers	in μ	Material	Build-Up	Assembly			
Layer-1	35 μ	Copper		B			
	60 μ	Prepreg			(60 μ PrePreg-Type: 1080)		
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125)		
Layer-2	70 μ	Copper			A1		
	200 μ	L-FR4					
Layer-3	70 μ	Copper			A2		
	60 μ	Prepreg					
	60 μ	Prepreg					
Layer-4	70 μ	Copper				A3	
	200 μ	L-FR4					
	Layer-5	70 μ				Copper	
60 μ		Prepreg					
60 μ		Prepreg					
Layer-6	70 μ	Copper		A5			
	200 μ	L-FR4					
	Layer-7	70 μ			Copper		A5
60 μ		Prepreg					
60 μ		Prepreg					
Layer-8	70 μ	Copper					
	200 μ	L-FR4					
	Layer-9	70 μ			Copper		
60 μ		Prepreg					
60 μ		Prepreg					
Layer-10	70 μ	Copper					
	200 μ	L-FR4					
	Layer-11	70 μ			Copper		
100 μ		Prepreg					
60 μ		Prepreg					
Layer-99	35 μ	Copper					

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